

INCH-POUND

MIL-C-47175A (MI)

AMENDMENT 2

02 September 1999

## MILITARY SPECIFICATION

### COMPOUND, POLYURETHANE, FOR CONFORMAL COATING OF ELECTRONIC CIRCUITRY

*This amendment forms a part of MIL-C-47175A, dated 10 November 1980, and is approved for use by the Aviation and Missile Command (AMCOM), Department of the Army, and is available for use by all Departments and Agencies of the Department of Defense. MIL-C-47175A remains inactive for new design, and is no longer used, except for replacement purposes, per Notice 2, dated 18 April 1996.*

Page 2, paragraph 2.1: Under Issues of documents:

Delete: "QQ-S-571 Solder, Tin Alloy, Lead-Tin Alloy and Lead Alloy"

Delete: "MIL-F-14256 Flux, Soldering, Liquid (Rosin Base)"

Delete: "MIL-P-18177 Plastic Sheet, Laminated, Thermosetting,, Glass Fiber Base, Epoxy Resin"

Delete: "MIL-STD-105 Sampling Procedures and Tables for Inspection by Attributes"

Page 2, after specifications Military:

Add: "MIL-I-24768/2 Insulation, Plastic, Laminated, Thermosetting, Glass-Cloth, Epoxy-Resin (GEE)"

Add: "MIL-I-24768/3 Insulation, Plastic, Laminated, Thermosetting, Glass-Cloth, Epoxy-Resin (GEB)"

Page 1 of 3

AMSC N/A

FSC 9330

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MIL-C-47175A(MI)  
AMENDMENT 2

Page 3, after specifications American Society for Testing and Materials:

Delete: "(Application for copies should be addressed to the American Society for Testing and Materials, 1916 Race Street, Philadelphia 19103)"

Replace with: "(Applications for copies should be addressed to the American Society for Testing and Materials, 100 Barr Harbor Drive, West Conshohocken, PA 19428-2959)"

Page 3, after the ASTM address, and before the last paragraph of 2.2:

Add: "American National Standards Institute

ANSI J-STD-004            Requirements for Soldering Fluxes

ANSI J-STD-005            Requirements for Soldering Pastes

ANSI J-STD-006            Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications

ANSI/ASQC Z1.4-1993    Sampling Procedures and Tables for Inspection by Attributes.

(Applications for copies should be addressed to the Institute for interconnecting and Packaging Electronic Circuits (IPC), 7380 N. Lincoln Avenue, Lincolnwood, IL 60646.)"

Page 6, Paragraph 4.3.2, end of 1<sup>st</sup> sentence:

Delete: "MIL-STD-105"

Replace with: "ANSI/ASQC Z1.4-1993"

Page 7, Paragraph 4.5.3, subparagraph a.:

Delete: "MIL-P-18177"

Replace with: "MIL-I-24768/2 or MIL-I-24768/3"

MIL-C-47175A(MI)  
AMENDMENT 2

Page 7, Paragraph 4.5.3, subparagraph b.:

Delete: "MIL-F-14256"

Replace with: "ANSI J-STD-004, ANSI J-STD-005, or ANSI J-STD-006"

Page 7, Paragraph 4.5.3, subparagraph b.:

Delete: "QQ-S-571"

Replace with: "ANSI J-STD-004, ANSI J-STD-005, or ANSI J-STD-006"

Custodian  
Army – MI

Review Activities:  
DLA – GS

Preparing Activity  
Army – MI

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